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OCTOBER 3, 2003

DATE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
 Olof Tornblad et al.

Serial No.:

Serial No.:

Filing Date: October 3, 2003

Title: LDMOS Transistor

Attny. Docket No. 068736.0231

Client Ref.: 2003P52734US

INFORMATION DISCLOSURE STATEMENT

Sir:

Applicants respectfully request, pursuant to 37 C.F.R. §§1.56, 1.97 and 1.98, that the art listed on the attached PTO-1449 form be considered and cited in the examination of the above-identified application. A copy of the cited art is enclosed for the convenience of the Examiner.

Furthermore, pursuant to 37 C.F.R. §§1.97(g) and (h), no representation is made that these references are material to the patentability of the present application.

As the Information Disclosure Statement is being submitted before the mailing of the first office action on the merits, Applicants believe that no fee is required. If a fee is required, please accept this transmittal as a petition therefor and charge any fee to Baker Botts L.L.P. (formerly, Baker & Botts, L.L.P.) Deposit Account No. 02-0383, Order No. (068736.0231) for any other charges necessary for the filing of this Information Disclosure Statement.

BAKER BOTTS L.L.P. (023640)

Date: October 3, 2003

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Client Reference No. 068736.0231 **PATENT** Application No. Applicant(s): PTO-1449 OLOF TORNBLAD ET AL. Information Disclosure Citation Group Art Unit Filing Date Docket Number in an Application 068736.0231 October 3, 2003 **U.S. PATENT DOCUMENTS CLASS SUBCLASS** FILING DATE DOCUMENT NO. DATE NAME 1 4,811,075 03/07/89 Eklund 357 46 04/24/87 2 10/13/92 Davies et al. 357 23.4 03/18/91 5,155,563 3 05/17/94 257 262 02/16/93 5,313,082 Eklund 4 Rumennik et al. 188 02/05/99 6,168,983 01/02/01 438 5 05/13/03 257 342 11/12/02 6,563,171 Disney FOREIGN PATENT DOCUMENTS TRANSLATION DOCUMENT NO. **CLASS SUBCLASS** DATE **COUNTRY** YES NON-PATENT DOCUMENTS DOCUMENT (Including Author, Title, Source, and Pertinent Pages) DATE J.A. Appels and H.M.J. Vaes, "High voltage thin layer devices (RESURF devices)", IEDM 1979 technical digest, pp. 238-241 H.M.J. Vaes and J.A. Appels, "High voltage high current lateral devices", IEDM technical 7 1980 digest, pp. 87-90 T. Fujihira, "Theory of Semiconductor Superjunction Devices", Jpn. J. Appl. Phys., vol. 36, pp. 1997 pp. 6254-6262 G. Deboy, M. Marz, J.-P. Stengl, H. Strack, J. Tihanyi and H. Weber, "A new generation of high 1998 voltage MOSFETs breaks the limit line of silicon", IEDM technical digest, pp. 683-685 A. Ludikhuize, "A review of RESURF technology", Proc. of ISPSD, p. 11 2000 10 J. Cai, C. Ren, N. Balasubramanian and J.K.O. Sin, "A novel high performance stacked LDD RF 11 2001 LDMOSFET, IEEE Electron Device Lett., vol. 22, no. 5, pp. 236-238 J.G. Mena and C.A.T. Salama, "High voltage multiple-resistivity Drift-Region LDMOS", Solid 1986 12 State Electronics, Vol. 29, No. 6, pp. 647-656 M.D. Pocha and R.W. Dutton, "A computer-aided design model for High-Voltage Double 1976 13 Diffused MOS (DMOS) Transistors", IEEE Journal of Solid-State Circuits, Vol. SC-11, No. 5 I. Yoshia, M. Katsueda, S. Ohtaka, Y. Maruyama and T. Okabe; "High Efficient 1.5 GHz Si Power MOSFET for Digital Cellular Front End"; Proceedings of International Symposium on 1992 14 Power Semiconductor Devices & ICs; Tokyo, pp. 156-157 **EXAMINER DATE CONSIDERED**

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not

considered. Include copy of this form with next communication to the applicant.